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The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

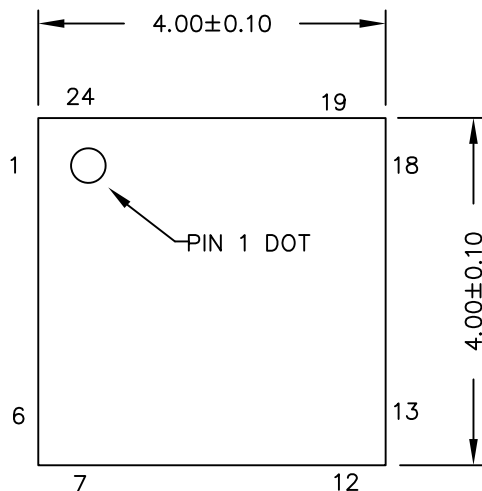
Continuity of document content

The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

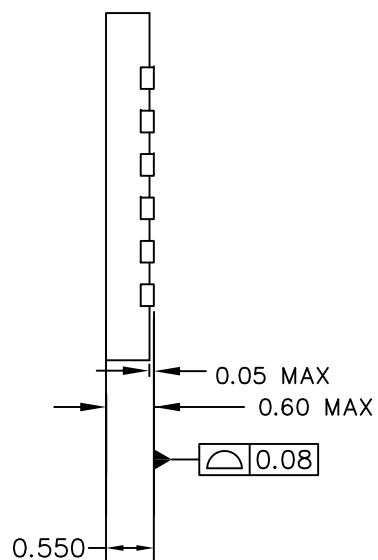
Continuity of ordering part numbers

Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.

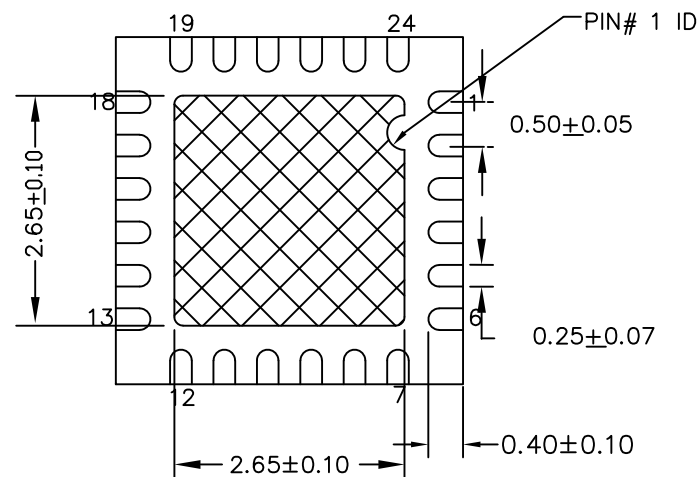
TOP VIEW




SIDE VIEW



BOTTOM VIEW



NOTES :

1.  HATCH IS SOLDERABLE EXPOSED METAL.
2. REFERENCE JEDEC # MO-248
3. PACKAGE WEIGHT : 29 ± 3 mg
4. ALL DIMENSIONS ARE IN MILLIMETERS

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PACKAGE CODE(S)

LQ24A

LQ24B



CYPRESS
Company Confidential

TITLE PACKAGE OUTLINE, 24L QFN 4X4X0.60 MM LQ24A/LQ24B
2.65X2.65 EPAD (SAWN)

SPEC NO. 001-13937

REV *H

SCALE SHEET 1 OF 2

Rev	ECN No.	Orig. of change	Description of Change
**	886880	JSO	NEW SPEC
*A	935762	JSO	ADDED UNIT PACKAGE WEIGHT 0.024 GRAMS
*B	2515796	JSO	UPDATED SPEC TITLE AND FIX DIMENSION FORMAT
*C	2812921	TZWTMP3	CHANGE TEMPLATE, CHANGE TITLE FROM 24L QFN 4 X 4 X 0.55MM PACKAGE OUTLINE 2.65X2.65 EPAD (SAWN TYPE) TO PACKAGE OUTLINE, 24L QFN 4X4X0.55 MM LQ24A 2.65X2.65 EPAD (SAWN)
*D	3569974	JSO	Removed package unit weight and added a note to refer to PMDD posted in CY web
*E	3670601	MLA	FORMAT REVISION, PER MEMO MLA-770Removed package unit weight and added a note to refer to PMDD posted in CY web
*F	4731466	ROWI	Sunset Review, Changed Drawing Template.
*G	6111055	SIGU	Changed title page from PACKAGE OUTLINE, 24L QFN 4X4X0.55 MM LQ24A 2.65X2.65 EPAD (SAWN) to PACKAGE OUTLINE, 24L QFN 4X4X0.60 MM LQ24A 2.65X2.65 EPAD (SAWN)
*H	6808256	KOTA	Add package code LQ24B

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SHEET 2 OF 2